

#18/Amended  
4-2-03  
JAL



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of:

Abbott, et al.

Serial No.: 09/525,105

Filed: 03/14/00

Docket No.: TI-28098


Examiner: Williams, A.O.

Art Unit: 2826

For: Semiconductor Circuit Assembly Having a Plated Leadframe Including Gold  
Selectively Covering Areas to be Soldered (as amended)

Amendment under 37 CFR 1.111

Assistant Commissioner of Patents  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)  
I hereby certify that this correspondence is being deposited with the  
U.S. Postal Service as First Class Mail in an envelope addressed to:  
Assistant Commissioner for Patents, Washington, D.C. 20231 on  
3-17-03  
  
Michael K. Skrehot, Reg. No. 36,682

Dear Sir:

The following amendments and remarks are offered in response to the Examiner's Office Action dated 12/17/02. They are respectfully submitted as a full and complete response to that Action. The Commissioner is hereby requested and authorized to charge any fees necessary for the filing of the enclosed papers to deposit account number 20-0668 of Texas Instruments Incorporated.

RECEIVED  
MAR 27 2003  
TECHNOLOGY CENTER 2800